



PRESS RELEASE

BE Semiconductor Industries N.V. Announces Approval of Agenda Items at its 2019 Annual General Meeting of Shareholders

Duiven, the Netherlands, April 26, 2019 - BE Semiconductor Industries N.V. (the "Company" or "Besì") (Euronext Amsterdam: BESI; OTC: BESIY, Nasdaq International Designation), a leading manufacturer of assembly equipment for the semiconductor industry, today announced the approval of all agenda items at its Annual General Meeting of Shareholders held today ("AGM"). Key highlights included the approval of the dividend for the 2018 financial year and changes to the composition of its Supervisory Board.

Dividend 2018

The dividend proposal of € 1.67 per ordinary share for the 2018 financial year was approved at the AGM. Such dividend will be paid out wholly in cash and payments will start as of May 6, 2019. The following time table will be applicable with respect to the dividend payment:

- April 30, 2019 Ex-dividend quotation
- May 2, 2019 Record date for dividend eligibility (after market close)
- Starting May 6, 2019 Payment of cash dividend

Holders of ordinary shares will receive the dividend through their bank or broker in whose custody the shares are held on May 2, 2019 close of business (record date). The dividend will be made payable to them as of May 6, 2019 through ABN AMRO Bank N.V.

Changes in the Composition of Besì's Supervisory Board

At the AGM, shareholders approved changes to the composition of Besì's Supervisory Board including the resignation of Mr Tom de Waard and Mr Kin Wah Loh, the re-appointment of Mr Douglas Dunn and the appointment of Mr Lodewijk Hijmans van den Bergh as a new Supervisory Board member.

Mr De Waard, Chairman of Besì's Supervisory Board, resigned his membership position prior to the end of his current four-year term ending in 2020 today. Mr De Waard has served as a member of the Supervisory Board for nineteen years.

In addition, Mr Kin Wah Loh resigned his position as Supervisory Board member upon expiration of his second four-year term today.

The AGM approved the appointment of Mr Lodewijk Hijmans van den Bergh as a Supervisory Board member for a four-year term. It is the intention of the Supervisory Board to appoint Mr Hijmans van den Bergh as Chairman of Besì's Supervisory Board.



Mr Hijmans van den Bergh (1963) has been a partner at the law firm De Brauw Blackstone Westbroek Lawyers, Amsterdam, since 2016. He also served at such firm as a partner and lawyer between 1988 and 2009 in their the Hague, Amsterdam and London offices. Between 2009 and 2015, Mr Hijmans van den Bergh served as Chief Corporate Governance Counsel and Member of the Executive Board of Royal Ahold NV (Zaandam, the Netherlands). Mr Hijmans van den Bergh currently serves as a member of the Supervisory Board of HAL Holding NV (Vice Chairman). He is also Chairman of the Board of Utrechts Universiteitsfonds and Fortino Capital Partners N.V. and a member of the Supervisory Councils of NKI/AVL (Nederlands Kankerinstituut/Anthonie van Leeuwenhoek Ziekenhuis) and Luchtverkeersleiding Nederland (Netherlands Air Traffic Control). Prior board memberships included ICA AB (Sweden) and the Royal Concertgebouw Orchestra (Deputy Chairman). Mr Hijmans van den Bergh is considered independent for the purposes of the Dutch Corporate Governance Code.

In addition, the AGM approved the re-appointment of Mr Douglas Dunn as a Supervisory Board member for a two-year term. Mr Dunn was first appointed in 2009 and has served on Beside's Supervisory Board for 10 years. Mr Dunn has extensive experience in the semiconductor industry both as managing director and supervisory board member of many industry participants. In particular, his knowledge and understanding of the semiconductor equipment industry, management challenges and cycles have proved extremely valuable to Beside.

About Beside

Beside is a leading supplier of semiconductor assembly equipment for the global semiconductor and electronics industries offering high levels of accuracy, productivity and reliability at a low cost of ownership. The Company develops leading edge assembly processes and equipment for leadframe, substrate and wafer level packaging applications in a wide range of end-user markets including electronics, mobile internet, cloud server, computing, automotive, industrial, LED and solar energy. Customers are primarily leading semiconductor manufacturers, assembly subcontractors and electronics and industrial companies. Beside's ordinary shares are listed on Euronext Amsterdam (symbol: BESI). Its Level 1 ADRs are listed on the OTC markets (symbol: BESIY Nasdaq International Designation) and its headquarters are located in Duiven, the Netherlands. For more information, please visit our website at www.beside.com.

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